Document Number: SMAV1040-30C9 Preliminary Datasheet V2.0

1.0-4.0GHz, 30W, 50V GaN Fully matched PA Module

Description

The SMAV1040-30C9 is a 30-watt, single stage integrated Power Amplifier Module, designed for broad band applications, with frequencies from 1 to 4GHz. The module is 50 Ω input/output matched and requires minimal external components.

Innogration

When used at 28V ,it can enable >15W CW Psat across the same 1 to 4GHz.

The module implements wideband power amplifier in form of multi chips, housed in cost effective plastic open cavity package, offers a much lower cost than traditional MMIC solutions.

Please notice that

For CW, it is strongly recommended to solder device onto the heatsink directly

For Pulse, it is acceptable to solder device through high density metalized grounding vias

V _{ds} = 50V, V _{gs} =-3.04V,I _{dq} =30mA					
Pulse Peak Power,100us,10%					
Freq(MHz)	P-1(dBm)	P-1Gain(dB)	P-3(dBm)	P-3(W)	EFF (%)
1000	44.77	12.7	45.44	35.0	49.5
1500	44.49	13.3	45.52	35.6	46.2
2000	43.78	12.4	44.86	30.6	36.0
2500	43.97	13.1	45.41	34.7	41.0
3000	44.97	13.7	45.83	38.3	47.2
3500	45.07	14.0	45.90	38.9	51.2
4000	44.60	13.4	45.70	37.1	56.6

$V_{ds} = 50V, V_{qs} = -3.04V, I_{dq} = 30mA$						
	CW Power					
Freq(MHz)	P-1(dBm)	P-1Gain(dB)	P-3(dBm)	P-3(W)	EFF (%)	
1000	44.07	11.8	45.03	31.9	47.6	
1500	43.43	12.3	44.94	31.2	43.9	
2000	43.01	11.1	44.18	26.2	35.1	
2500	42.24	12.3	44.78	30.0	39.0	
3000	43.46	13.1	45.41	34.8	46.1	
3500	44.43	13.2	45.60	36.3	50.1	
4000	44.33	12.9	45.56	35.9	56.3	

Product Features

Operating Frequency Range: 1-4GHz
Operating Drain Voltage: +50 V / 28V

• 50 Ω Input/Output

• Psat≥30W (Pulse or CW)/ 15W(CW)

• Small signal gain:>13dB, Power gain:>9dB @50V

• Minimum efficiency:>35% @50V

• 12x10 mm Surface Mount Package

• Compliant to Restriction of Hazardous Substances (RoHS) Directive 2002/95/EC

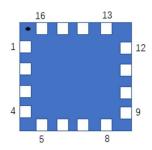
Applications

- Ultra Broadband Amplifiers
- Fiber Drivers
- Test Instrumentation
- EMC Amplifier Drivers
- · 2-way Radios

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Pin Configuration and Description (Top view)



Pin No.	Symbol	Description
4	RF IN	RF Input
9	RF OUT	RF Output
6	Vgs	Gate bias
7	Vdd	Drain bias
Others	NC	No connection
		DC/RF Ground. Proposed to be soldered to heatsink plane directly for the best CW thermal
Package Base	GND	and RF performance. Soldered through high density vias or copper coin also allowed ,but will
		result in excessive junction temperatures and different RF performance

Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
DrainSource Voltage	V _{DSS}	200	Vdc
GateSource Voltage	V _{GS}	-10 to +2	Vdc
Operating Voltage	V _{DD}	+55	Vdc
Storage Temperature Range	Tstg	-65 to +150	°C
Case Operating Temperature	Tc	+150	°C
Operating Junction Temperature	T₃	+225	°C

Table 2. Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case	Rejc	2.0	°C/W
T _C = 85°C, DC test, soldered on heatsink directly	RejC	2.8	

Table 3. Electrical Characteristics

Parameter	Condition	Min	Тур	Max	Unit
Frequency Range		1000		4000	MHz
Power Gain @ Psat		10			dB
P _{SAT}	Pulse		45		dBm
Drain Efficiency @ P _{SAT}		35			%
Unless otherwise noted: TA = 25°C, V _{DD} =50 V, Pulse Width=100 us, Duty cycle=10%					

Load Mismatch of per Section (On Test Fixture, 50 ohm system): $V_{DD} = 50V$, $I_{DQ} = 30$ mA, f = 3.5 GHz

VSWR 10:1 at Psat pulse CW Output Power	No Device Degradation
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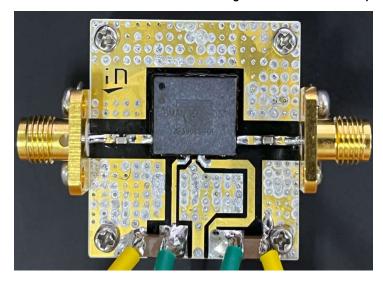


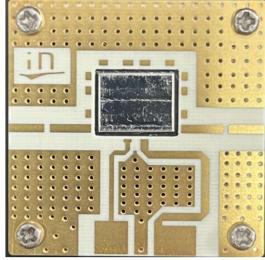
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Reference Circuit of Test Fixture Assembly Diagram

Figure 1. Test Circuit Component Layout





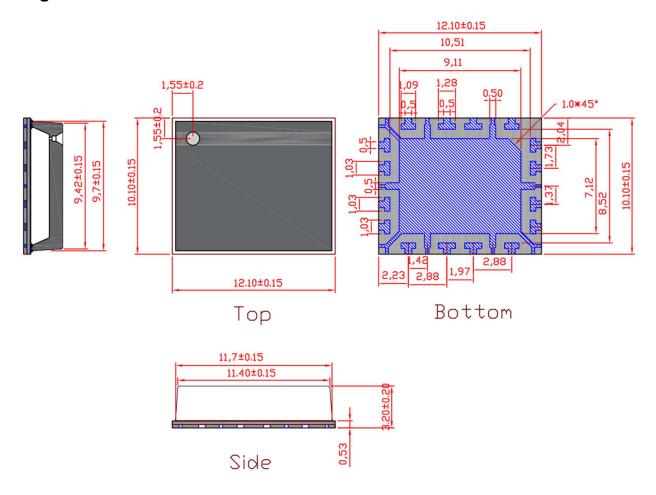
TYPICAL CHARACTERISTICS

Figure 2. Network analyzer output S11/S21 (Pin=0dBm) at 50V



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Package Dimensions (Unit:mm)



Revision history

Table 6. Document revision history

Date	Revision	Datasheet Status
2023/5/5	Rev 1.0	Preliminary Datasheet
2024/8/21	Rev 2.0	Update to be CW capable by soldering device onto heatsink

Application data based on HJ-23-07

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